

Temperature Measurement
B57620
SMD NTC Thermistors with Silver Palladium Termination, Size 0805
C 620


R_{25} Ω	No. of R/T characteristic	$B_{25/50}$ K	$B_{25/85}$ K	$B_{25/100}$ K	Ordering code
10 k	1011	3660	3730	3730	B57620C0103+062
22 k	2003	3930	3960	3980	B57620C0223+062
47 k	2101	4030	4080	4100	B57620C0473+062
100 k	2903	4120	4190	4200	B57620C0104+162
220 k	2904	4230	4280	4300	B57620C0224+062

+: J for $\Delta R_N/R_N = \pm 5\%$
 K for $\Delta R_N/R_N = \pm 10\%$
 M for $\Delta R_N/R_N = \pm 20\%$

Reliability data

SMD NTC thermistors are tested in accordance with IEC 60068. The parts are mounted on a standardized PCB in accordance with IEC 60539-1.

Test	Standard	Test conditions	$\Delta R_{25}/R_{25}$ (typical)	Remarks
Storage in dry heat	IEC 60068-2-2 JIS C 0021	Storage at upper category temperature $T: (125 \pm 2)^\circ\text{C}$ $t: 1000\text{ h}$	$< 3\%$ / $< 6\%^1$	
Storage in damp heat, steady state	IEC 60068-2-3 JIS C 0022	Temperature of air: $(40 \pm 2)^\circ\text{C}$ Relative humidity of air: $(93 +2/-3)\%$ Duration: 21 days	$< 3\%$	No visible damage
Rapid temperature cycling	IEC 60068-2-14 JIS C 0025	Lower test temperature: -55°C Upper test temperature: 125°C Number of cycles: 10	$< 3\%$	
Endurance		$P_{\max}$: 210 mW $T: (65 \pm 2)^\circ\text{C}$ $t: 1000\text{ h}$	$< 5\%$	
Solderability	IEC 60068-2-58 JIS C 0054	Solderability: $(215 \pm 3)^\circ\text{C} / (3 \pm 0,3)\text{ s}$ $(235 \pm 5)^\circ\text{C} / (2 \pm 0,2)\text{ s}$ Resistance to soldering heat: $(260 \pm 5)^\circ\text{C} / (10 \pm 1)\text{ s}$		95 % of terminations wetted
Resistance drift after soldering		Reflow soldering profile Wave soldering profile	$< 5\%$	

1) The higher value applies to 220 Ω –1 k Ω types.